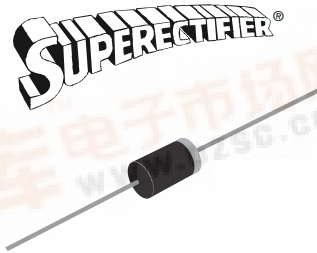




# BYV26DGP & BYV26EGP

Vishay General Semiconductor

## Glass Passivated Ultrafast Rectifier



DO-204AC (DO-15)

\* Glass Encapsulation technique is covered by Patent No. 3,996,602, brazed-lead assembly to Patent No. 3,930,306

### FEATURES

- Cavity-free glass-passivated junction
- Ultrafast reverse recovery time
- Low forward voltage drop
- Low switching losses, high efficiency
- High forward surge capability
- Meets environmental standard MIL-S-19500
- Solder dip 260 °C, 40 s
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS COMPLIANT

### TYPICAL APPLICATIONS

For use in high frequency rectification and freewheeling application in switching mode converters and inverters for consumer, computer and telecommunication.

### MECHANICAL DATA

**Case:** DO-204AC, molded epoxy over glass body

Epoxy meets UL 94V-0 flammability rating

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD22-B102

E3 suffix for consumer grade, meets JESD 201 class 1A whisker test, HE3 suffix for high reliability grade (AEC Q101 qualified), meets JESD 201 class 2 whisker test

**Polarity:** Color band denotes cathode end

### PRIMARY CHARACTERISTICS

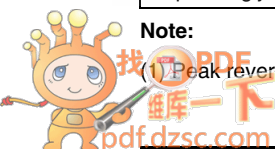
$I_{F(AV)}$	1.0 A
$V_{RRM}$	800 V, 1000 V
$I_{FSM}$	30 A
$t_{rr}$	75 ns
$V_F$	1.3 V
$T_J \text{ max.}$	175 °C

### MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	BYV26DGP	BYV26EGP	UNIT
Maximum repetitive peak reverse voltage	$V_{RRM}$	800	1000	V
Maximum RMS voltage	$V_{RMS}$	560	700	V
Maximum DC blocking voltage	$V_{DC}$	800	1000	V
Maximum average forward rectified current 0.375" (9.5 mm) lead length (Fig. 1)	$I_{F(AV)}$	1.0		A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	30		A
Non repetitive peak reverse energy <sup>(1)</sup>	$E_{RSM}$	10		mj
Operating junction and storage temperature range	$T_J, T_{STG}$	- 65 to + 175		°C

**Note:**

(1) Peak reverse energy measured at  $I_R = 400 \text{ mA}$ ,  $T_J = T_J \text{ max.}$  on inductive load,  $t = 20 \text{ } \mu\text{s}$



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<b>ELECTRICAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	BYV26DGP	BYV26EGP	UNIT
Minimum avalanche breakdown voltage	100 $\mu\text{A}$		$V_{BR}$	900	1100	V
Maximum instantaneous forward voltage	1.0 A	$T_J = 25\text{ }^\circ\text{C}$ $T_J = 175\text{ }^\circ\text{C}$	$V_F$	2.5 1.3		V
Maximum DC reverse current at rated DC blocking voltage		$T_A = 25\text{ }^\circ\text{C}$ $T_A = 165\text{ }^\circ\text{C}$	$I_R$	5.0 150		$\mu\text{A}$
Max. reverse recovery time	$I_F = 0.5\text{ A}$ , $I_R = 1.0\text{ A}$ , $I_{rr} = 0.25\text{ A}$		$t_{rr}$	75		ns
Typical junction capacitance	4.0 V, 1 MHz		$C_J$	15		pF

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	BYV26DGP	BYV26EGP	UNIT
Typical thermal resistance <sup>(1)(2)</sup>	$R_{\theta JA}$ $R_{\theta JL}$	70 16		$^\circ\text{C/W}$

**Notes:**

- (1) Thermal resistance from junction to ambient at 0.375" (9.5 mm) lead length, mounted on P.C.B. with 0.5 x 0.5" (12 x 12 mm) copper pads
- (2) Thermal resistance from junction to lead at 0.375" (9.5 mm) lead length with both leads attached to heatsink

<b>ORDERING INFORMATION</b> (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
BYV26EGP-E3/54	0.428	54	4000	13" diameter paper tape and reel
BYV26EGP-E3/73	0.428	73	2000	Ammo pack packaging
BYV26EGPHE3/54 <sup>(1)</sup>	0.428	54	4000	13" diameter paper tape and reel
BYV26EGPHE3/73 <sup>(1)</sup>	0.428	73	2000	Ammo pack packaging

**Note:**

- (1) Automotive grade AEC Q101 qualified

## RATINGS AND CHARACTERISTICS CURVES

( $T_A = 25\text{ }^\circ\text{C}$  unless otherwise noted)

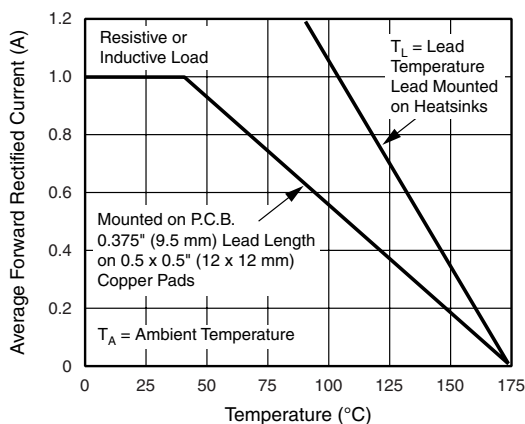


Figure 1. Maximum Forward Current Derating Curve

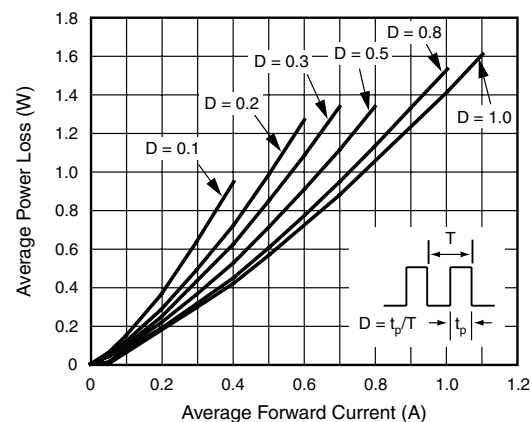


Figure 2. Forward Power Loss Characteristics



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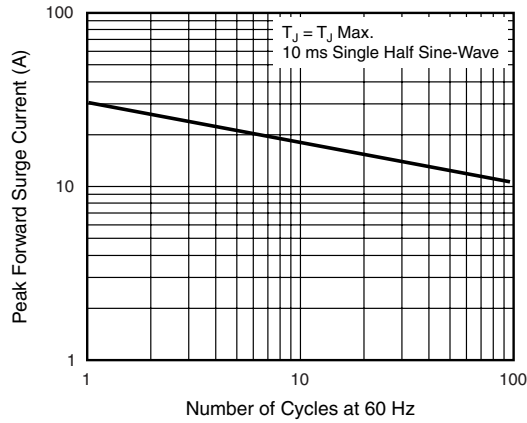


Figure 3. Maximum Non-Repetitive Peak Forward Surge Current

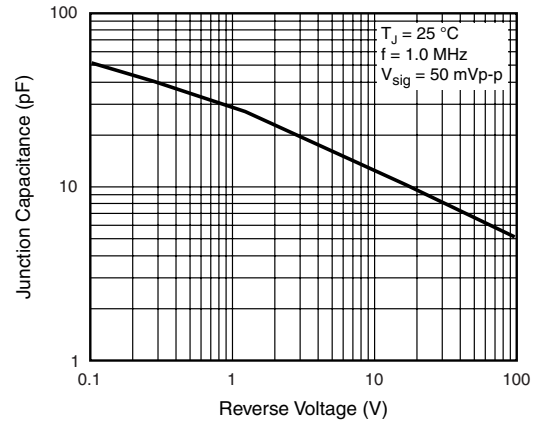


Figure 6. Typical Junction Capacitance

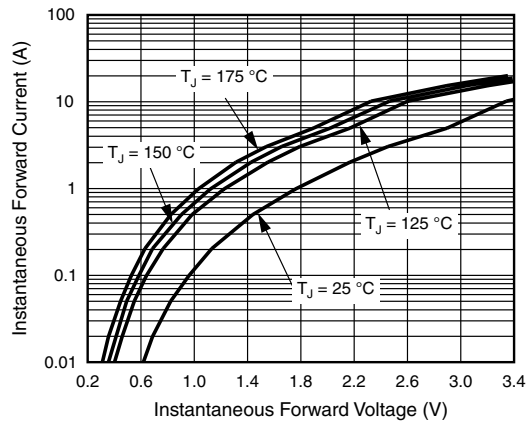


Figure 4. Typical Instantaneous Forward Voltage Characteristics

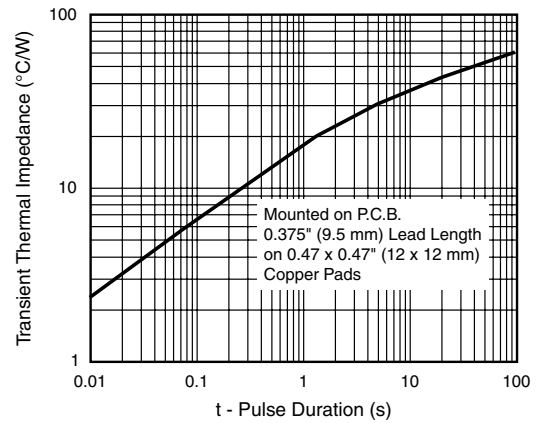


Figure 7. Typical Transient Thermal Impedance

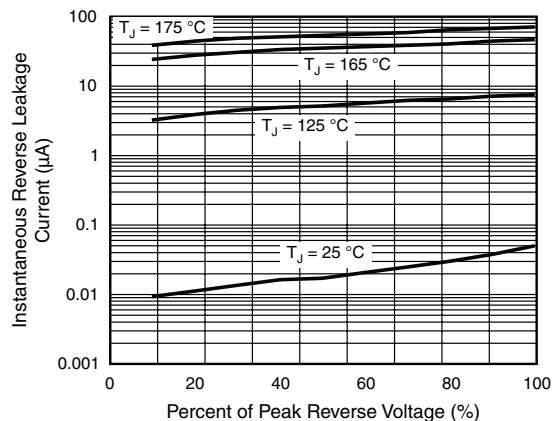


Figure 5. Typical Reverse Leakage Characteristics

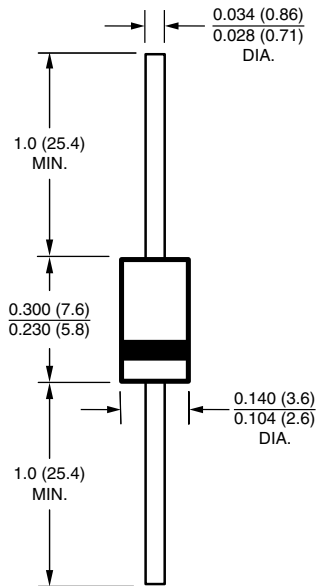
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## PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

### DO-204AC (DO-15)





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